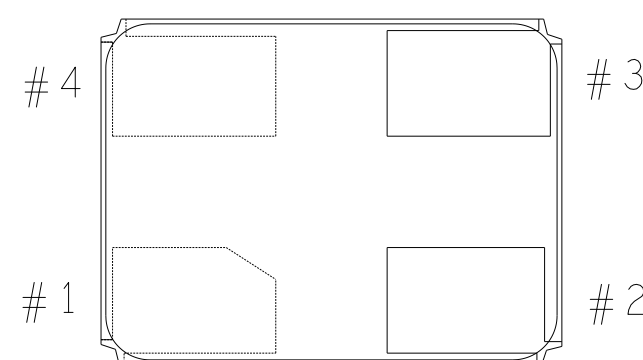


REVISIONS				
REV	DESCRIPTION		DATE	APPROVED
A	INITIAL RELEASE: NHR-059241		12/6/19	J. CHONG
B	ECR-093672		18MAR20	J. CHONG
C	ECR-095003		18MAY20	J. CHONG


Note: Actual device pin #1 has a chamfered corner terminal as shown.



Y SML 98W79H26

NX2520SA-19.200000MHZ-NBG1

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES			APPROVAL		DATE		 ANALOG DEVICES		WWM DIVISION 804 WOBBURN STREET WILMINGTON, MA 01887					
TOLERANCES			TEMPLATE ENGINEER				<div>TITLE</div> <div>ASSEMBLY FX3-ISENSOR-POD CUSTOMER EVALUATION Z</div>							
DECIMALS	FRACTIONS	ANGLES	HARDWARE SERVICES											
.XX --.010	--1/32	-- 2	HARDWARE SYSTEMS											
.XXX --.005														
.XXXX --.0050														
MATERIAL			TEST ENGINEER											
			COMPONENT ENGINEER											
			TEST PROCESS											
			HARDWARE RELEASE											
FINISH			DESIGNER				SIZE		FSCM NO		DRAWING NUMBER		REV	
			PTD ENGINEER J. CHONG CHECKER		06DEC19		C		34031		01-059334-01		C	
DO NOT SCALE DWG							SCALE		1/1				SHEET 1 OF 1	

GENERAL ASSEMBLY NOTES:

1. THE PRINTED CIRCUIT BOARD SHALL BE ASSEMBLED USING INDUSTRY STANDARD BEST PRACTICES PER IPC-A 610 CLASS 2.
2. THE PRINTED CIRCUIT BOARD SHALL BE ASSEMBLED IN COMPLIANCE WITH ROHS STANDARDS FOR LEAD FREE PRODUCTS.
RECOMMENDED SOLDER COMPOSITION IS 96.5 SN / 3 AG / 0.5 CU OR EQUIVALENT.
3. THE PRINTED CIRCUIT BOARD ASSEMBLY SHALL BE CAPABLE OF STORAGE AT TEMPERATURES FORM -55* TO 150*.
4. FLUX SHALL BE USED FOR ALL SOLDERING, WATER SOLUBLE ORGANIC ACID FLUX.
5. THE FINAL ASSEMBLY SHALL BE FREE OF FLUX RESIDUE AND FOREIGN MATERIAL AND (20.00 UG/SQ INCH NACL EQUIVALENT).
6. TWO PART ADHESIVE SHALL BE USED UNDER USB CONNECTOR FOR REPITIVE CONNECTION FORCE ABSOBTION.
7. A CERTIFICATE OF COMPLIANCE SHALL BE SENT WITH EACH ASSEMBLY LOT.
8. SEE DETAIL A FOR Y1 PIN1 ORIENTATION.
9. RoHS COMPLIANCE: ASSEMBLY VENDOR SHOULD ASSURE COMPLIANCE WITH LEAD-FREE AND RoHS PCB ASSEMBLY STANDARDS (EU RoHS DIRECTIVE 2002/95/EC).